

# Team InteGrated-Electronic Response

<http://www.ecrc.gatech.edu/tiger/>



## Enabling Advanced Prime-Supplier Collaboration in TIGER Using STEP Product Model-Driven Analysis

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# Abstract

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The DARPA-sponsored TIGER project (Team Integrated Electronic Response) demonstrates advanced engineering collaboration between primes and suppliers using standards-based design and manufacturing tools. In the TIGER scenario, a large manufacturer provides its suppliers early printed wiring assembly/board (PWA/B) design information in a standard STEP format. Suppliers use the TIGER toolset via an Internet-based engineering bureau to supplement this information with their process expertise. They then perform a variety of process-specific design checks, including design-for-manufacturability (DFM) and thermomechanical analysis. As members of the product team, suppliers feedback design improvement suggestions via a negotiation facility.

This presentation overviews this prime-supplier interaction with an emphasis on product model-driven analysis and the underlying CAD/CAE integration techniques (illustrated via thermomechanical applications). Accomplishments include the world's first usage of the STEP draft standard for PWA/Bs (AP210 DIS) to drive DFM and Ansys finite element analyses - all using live data that originates in the Mentor Graphics circuit board layout tool. The electronic commerce context is also highlighted which deals with business aspects of collaborative engineering such as electronic request for proposals, technical data exchange, and Internet-based security.

The TIGER scenario has been tested with Boeing and Holaday Circuits as a representative prime and supplier, respectively. Other team members are Arthur D. Little, Atlanta Electronic Commerce Resource Center, Georgia Tech, International TechneGroup Inc., and South Carolina Research Authority. Related activities underway at the Atlanta Electronic Commerce Resource Center to support small businesses are included.

Experiences indicate TIGER leverages the expertise of suppliers to provide certain design checks that are more precise than those typically done by primes. The Internet-based engineering bureau offers these checks to suppliers on a cost-effective basis ranging from self-service (for highly automated routine analyses) to full- service (for challenging new analyses). This paradigm provides suppliers advanced capabilities without requiring expensive in-house tools and expertise. Overall, the advantage of TIGER techniques is the effective inclusion of suppliers in the product team, resulting in timely, cost-saving design improvements. Further information is available at <http://eislabs.gatech.edu/tiger/>

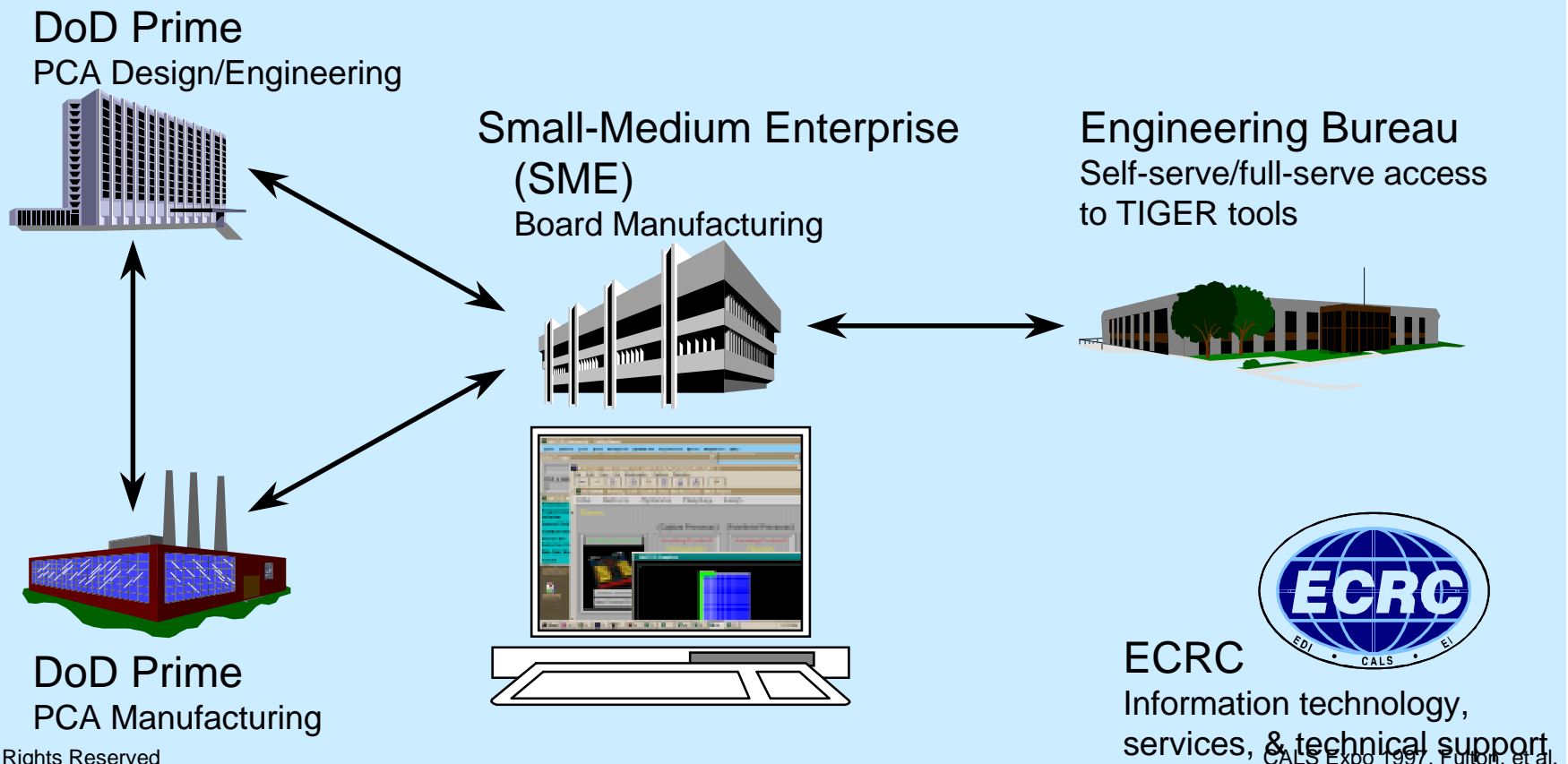


# TIGER: Advanced Engineering Collaboration



BAA 95-23

*... among DoD Primes & SMEs,  
using standards-based tools (TDI/EDI & STEP),  
facilitated by ECRC technology & services*





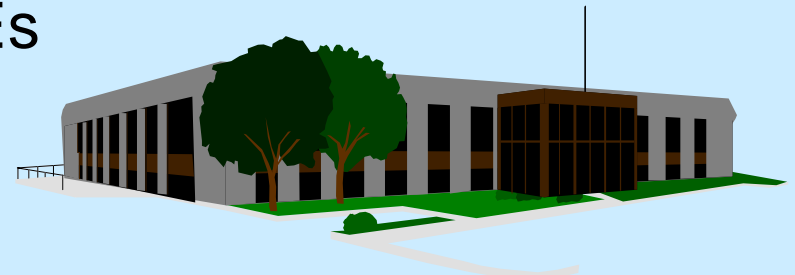
# Electronic Commerce Resource Centers (ECRCs)

## National Program

Provide assistance to government organizations and small-to-medium-sized businesses by introducing electronic commerce into their business practices

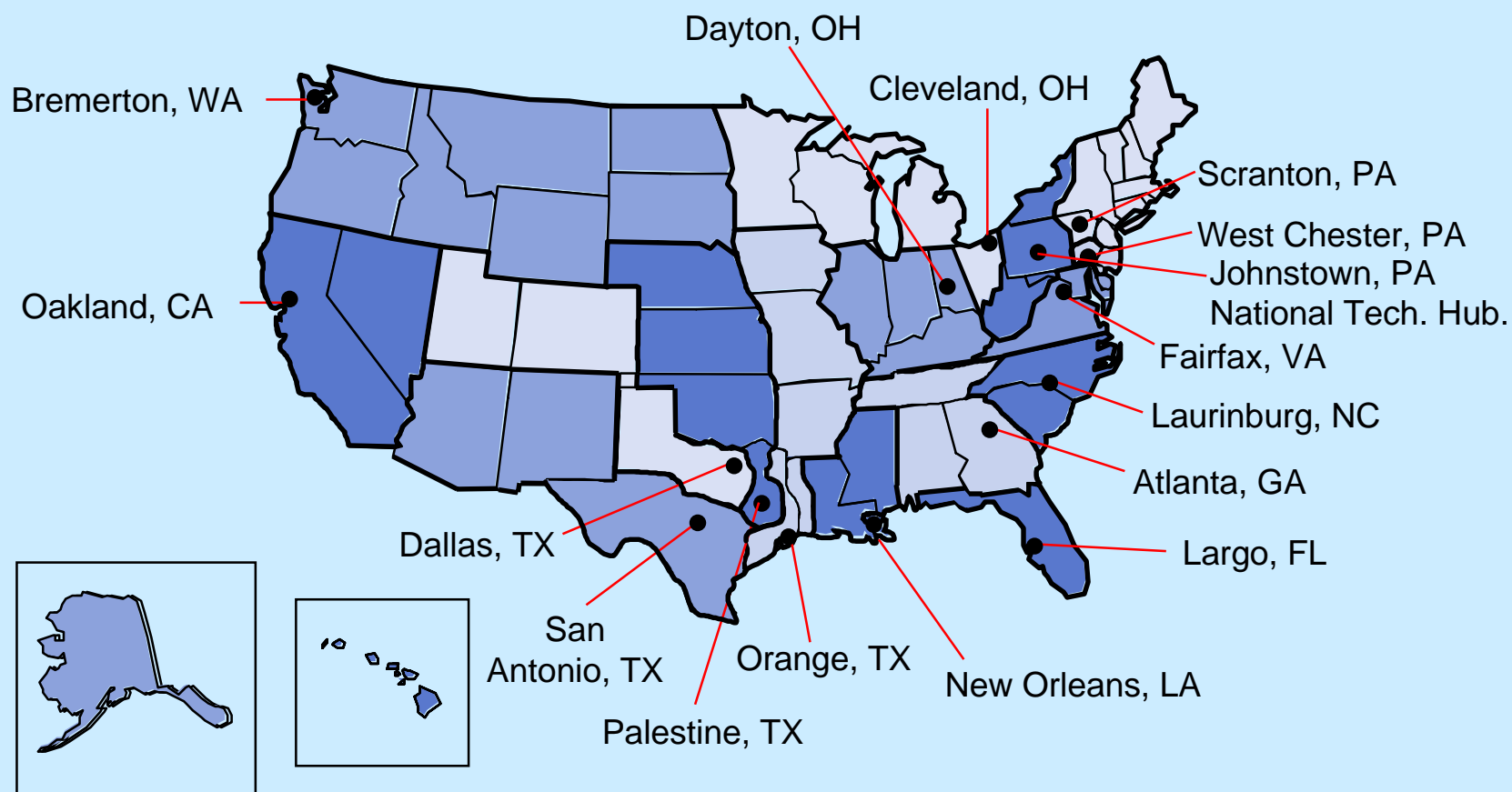
## Atlanta ECRC Role in TIGER

- Information technology support for SMEs (Small-Medium Enterprises)
- Demonstration engineering service bureau
- Technology transfer to SMEs



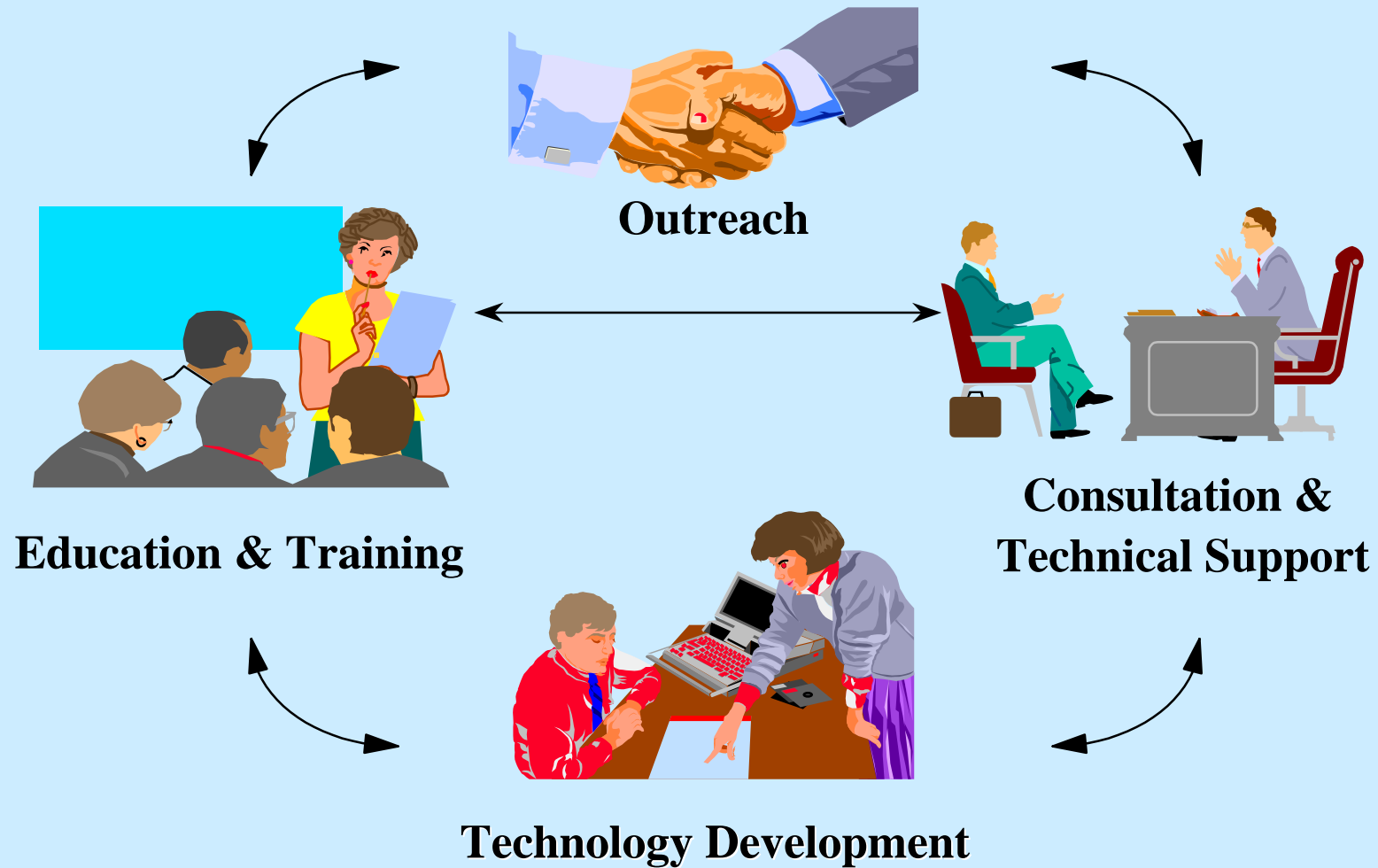


# Regional ECRCs





# ECRC Core Functions





# ECRC Course Curriculum

- Getting Started with Electronic Commerce
- Business Opportunities With the DoD Through EDI
- Electronic Funds Transfer
- Internet Basics for Small & Medium-sized Companies
- Technical Data Exchange
- Legacy Data Management
- STEP and Product Data Modeling



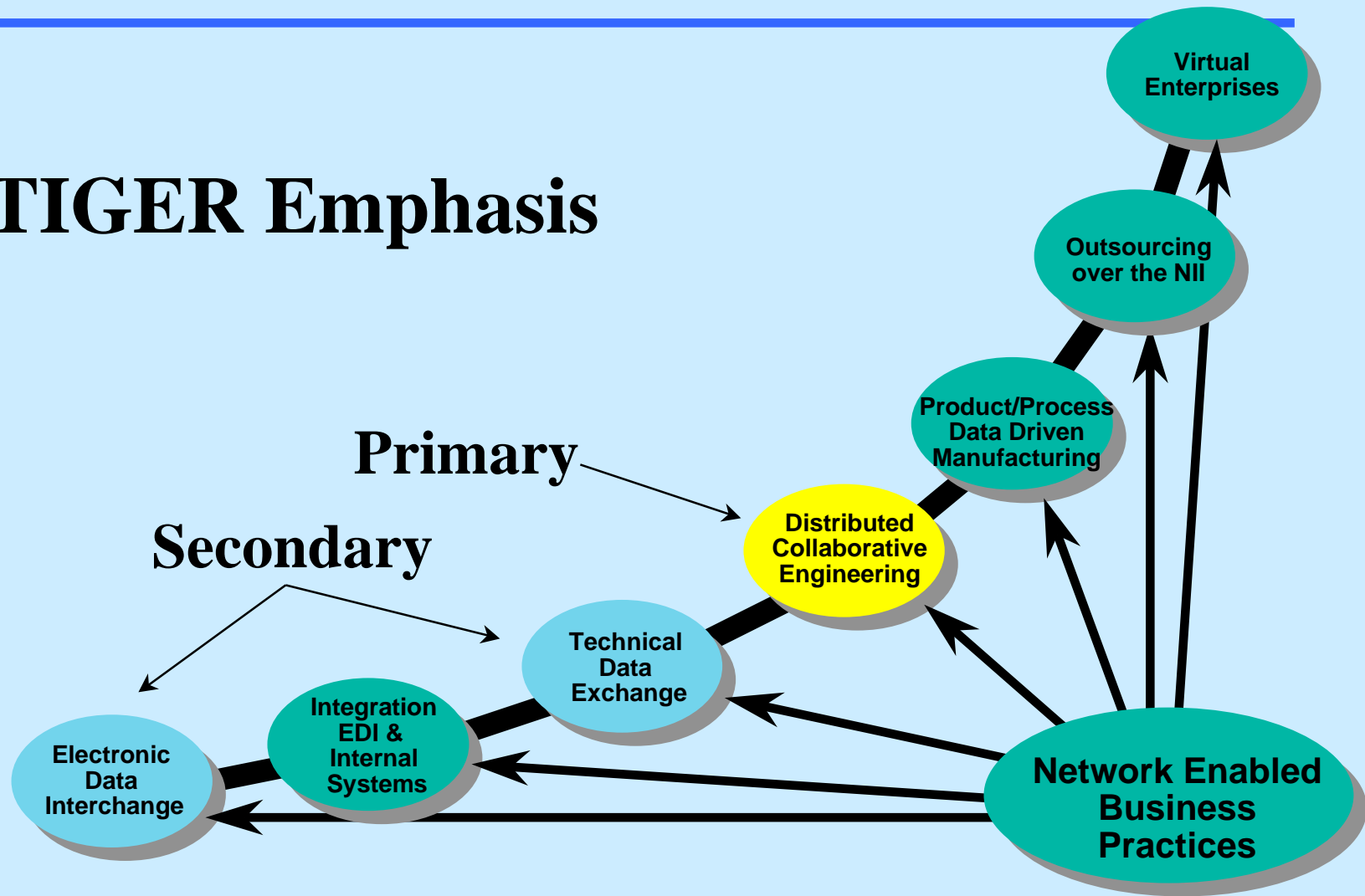
**Contacts for ECRC Services & Course Schedules:**

**Atlanta ECRC: [www.ecrc.gatech.edu](http://www.ecrc.gatech.edu), [ecrcinfo@ecrc.gatech.edu](mailto:ecrcinfo@ecrc.gatech.edu), 800-894-8042**

**National ECRC: [www.ecrc.ctc.com](http://www.ecrc.ctc.com)**

# Electronic Commerce Continuum

## TIGER Emphasis

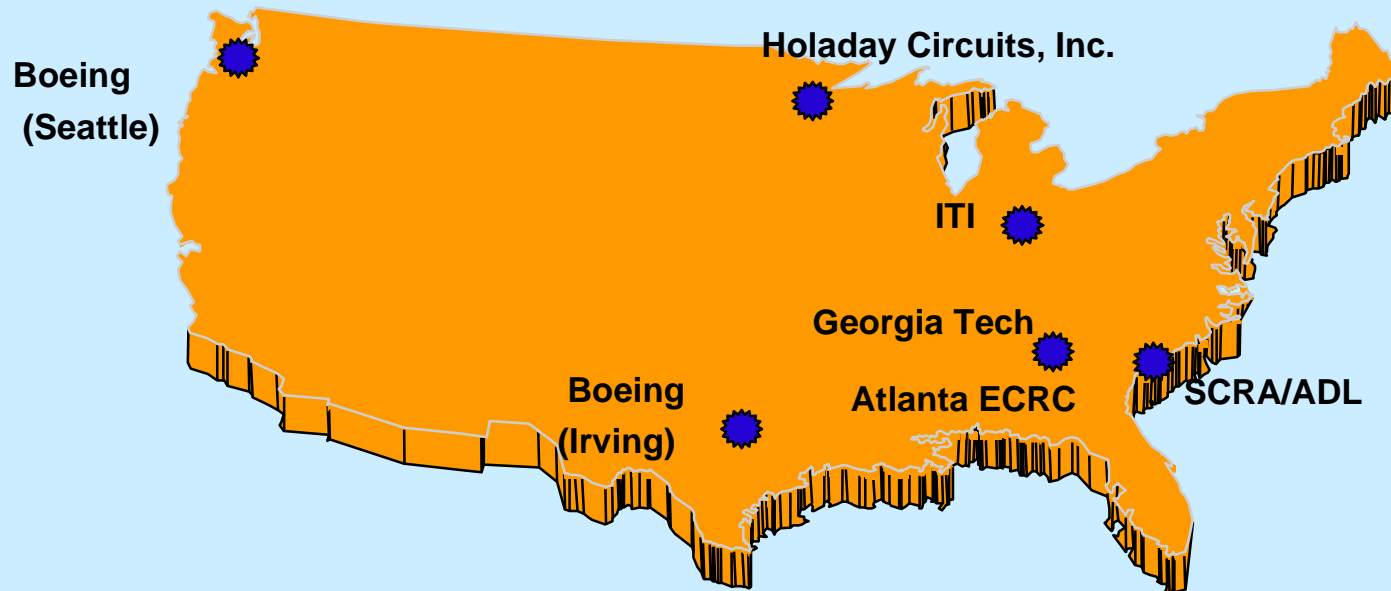






# Team InteGrated-Electronic Response

## TIGER Team Members



### Team Roles:

#### **Holaday**

- Pilot SME
- Board Mfg. Expert

#### **SCRA**

- Software Enhancement, Integration
- Technical Management
- Technical Support

#### **Boeing**

- Pilot DoD Prime
- Software Enhancement, Integration

#### **Georgia Tech**

- Analysis Tools
- Software Integration

#### **Atlanta ECRC**

- EC Services/Support
- Technology Transfer

#### **ITI**

- Software Development, Integration

#### **ADL**

- Technical Support
- Management Support

# STEP AP 210

## PCA Design Information

### Physical

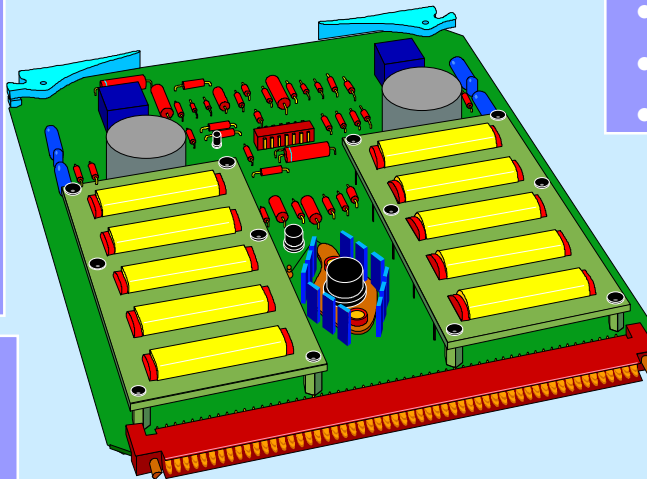
- Component Placement
- Bare Board Geometry
- Layout items
- Layers non-planar, conductive & non-conductive
- Material product

### Geometry

- Geometrically Bounded 2-D Shape
- Wireframe with Topology
- Advanced BREP Solids
- Constructive Solid Geometry

### Product Structure/Connectivity

- Functional
- Packaged



### Part

- Functionality
- Termination
- Shape 2D, 3D
- Single Level Decomposition
- Material Product
- Characteristics

### Configuration Mgmt

- Identification
- Authority
- Effectivity
- Control
- Requirement Traceability
- Analytical Model
- Document References

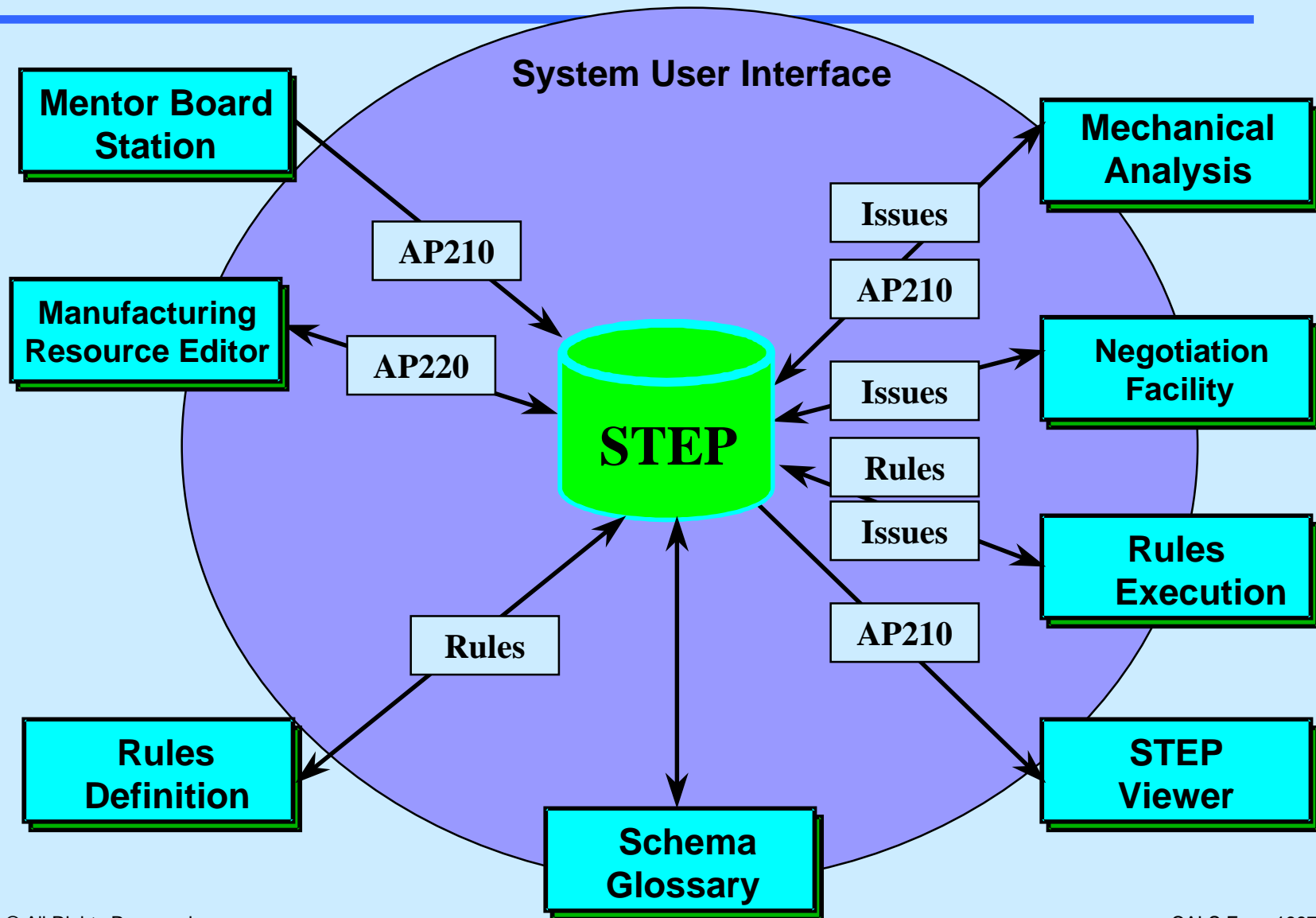
### Requirements

- Design
- Allocation
- Constraints
- Interface

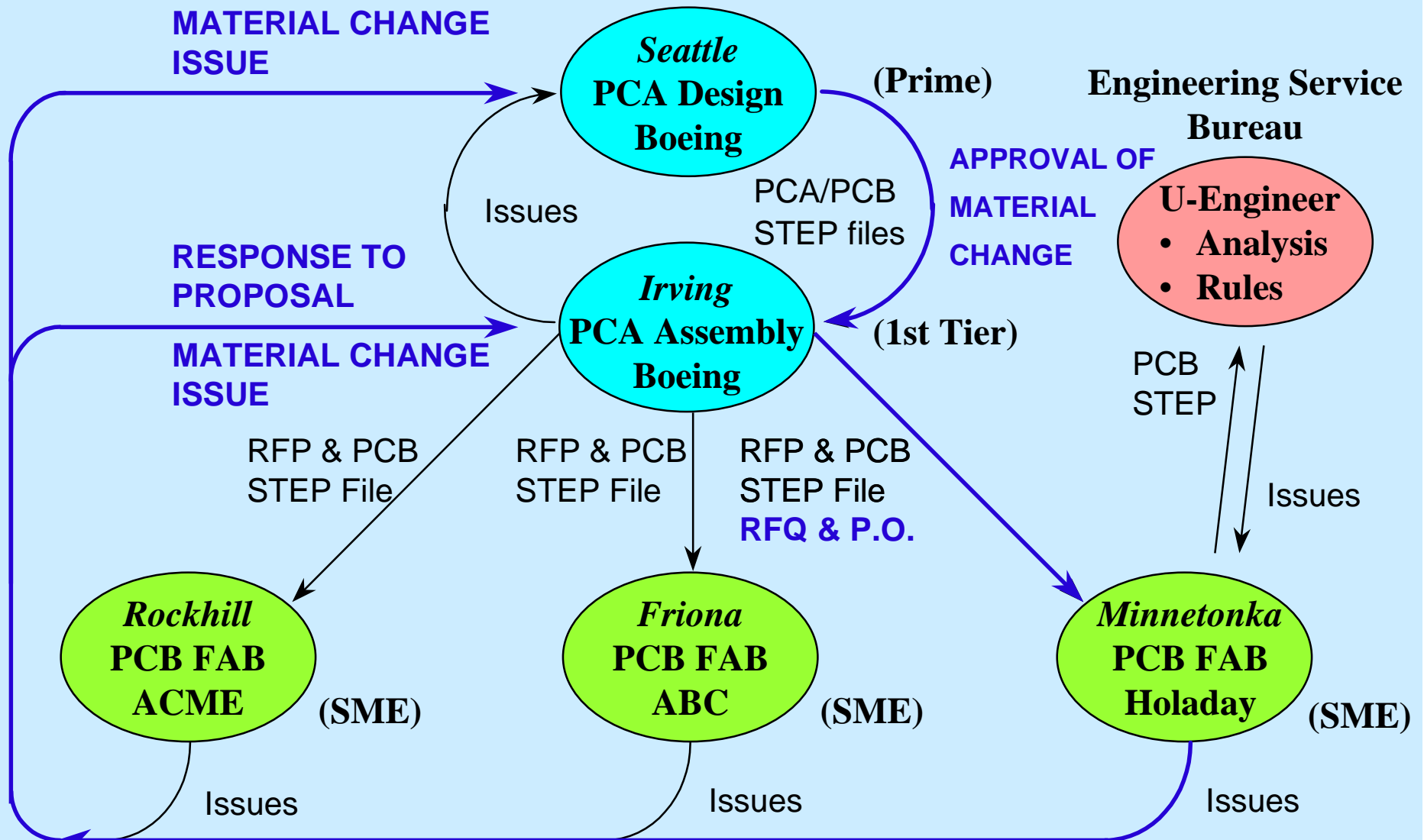
### Technology

- Fabrication Design Rules
- Product Design Rules

# TIGER Tool Architecture



# Collaborative Engineering Scenario



# Engineering Service Bureau

- Provides SMEs with cost effective, Internet-based access to TIGER Tools
- STEP-based
- Secure Data Transfer (encryption)
- Self-serve and Full-serve analysis
- Highly Automated PWA/B Analysis
  - Warpage Analysis
  - Plated Through Hole Fatigue
  - Solder Joint Stress Analysis

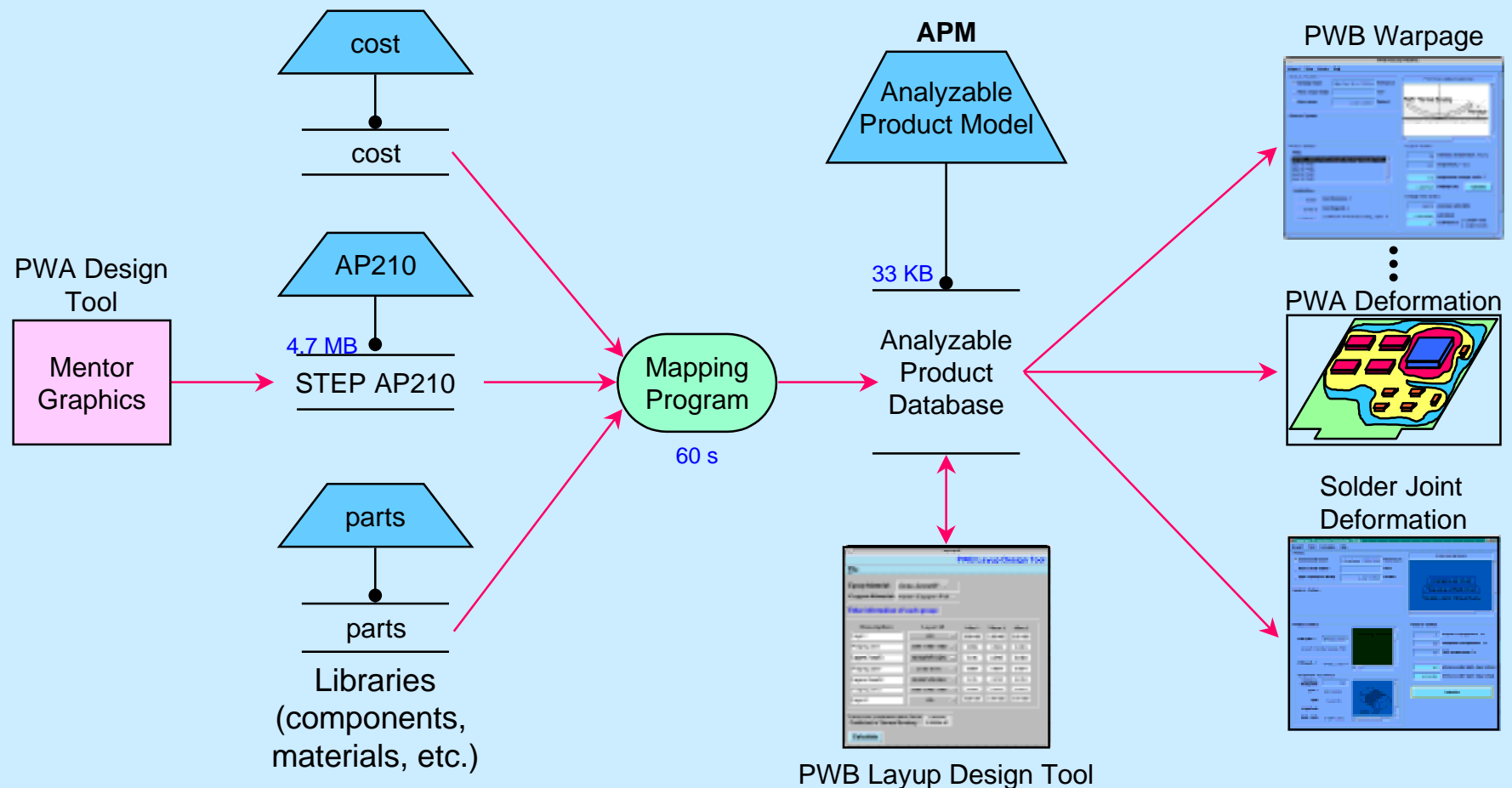


# STEP Product Data-Driven Analysis

## Design

## Mapping

## Analysis



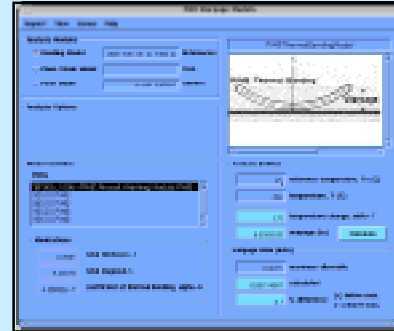
# Iterative Design & Analysis

PWB Layup Design Tool



Layup  
Redesign

Thermal Bending Model



Quick Formula-based Check

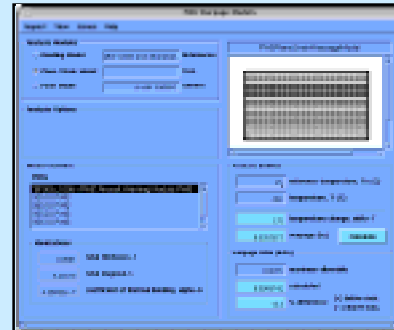
$$\delta = \frac{\alpha_b L^2 \Delta T}{t}$$

$$\alpha_b = \frac{\sum w_i \alpha_i y_i}{t / 2 \sum w_i}$$

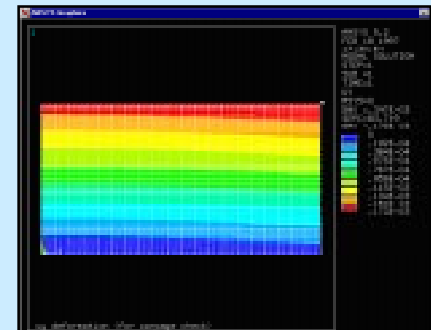
Analyzable  
Product  
Database

PWB Warpage Modules

Plain Strain Model



Accurate FEA Check



3 x 1080		1 Oz. Cu
		2 Oz. Cu
	Acme-AcmeGF	1 Oz. Cu
2 x 2116		1 Oz. Cu
		2 Oz. Cu
	Acme-AcmeGF	1 Oz. Cu
3 x 1080		2 Oz. Cu
		1 Oz. Cu

# Solder Joint Deformation Catalog: Plane Strain Model (FEA-based)

Component Occurrence Deformation PBAMs

Inspect View Help

**PBAMs**

- ☐ Extensional Model Lau, et. al. 1986 References
- ☒ Plane Strain Model psb.2 Case
- ☐ Solid Continuum Model a user context Context

**Analysis Options**

Solder Joint Geometry: ☒ rectangular ☐ detailed

Solder Stress-Strain Model: ☒ linear elastic ☐ bilinear plastic

**Product Entities**

PWA part #: 95145 Controller Main Board

PWB part #: 96510

**Component Occurrence**

reference designator: R106

part #: 99210

type: Resistor

magnitude: 100

body style: #SMD1206

**Analysis Entities**

PlaneStrainModel

To: Solder Joint: PSB  
Component: PSB Tc  
Substrate/PWB: PSB Ts  
(PSB = Plane Strain Body)

-55 reference temperature, To

125 component temperature, Tc

125 PWB temperature, Ts

-14480.0 extreme solder joint shear stress

-0.0270293 extreme solder joint shear strain

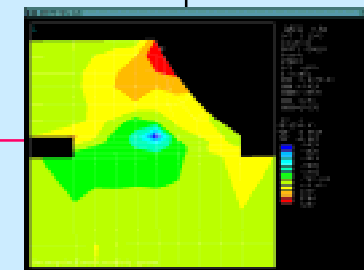
Calculate

Compare SMM Inputs

☐ Display Solution Graphics

☐ Simulate Solution Tool

FEA  
Tool  
(Ansys)

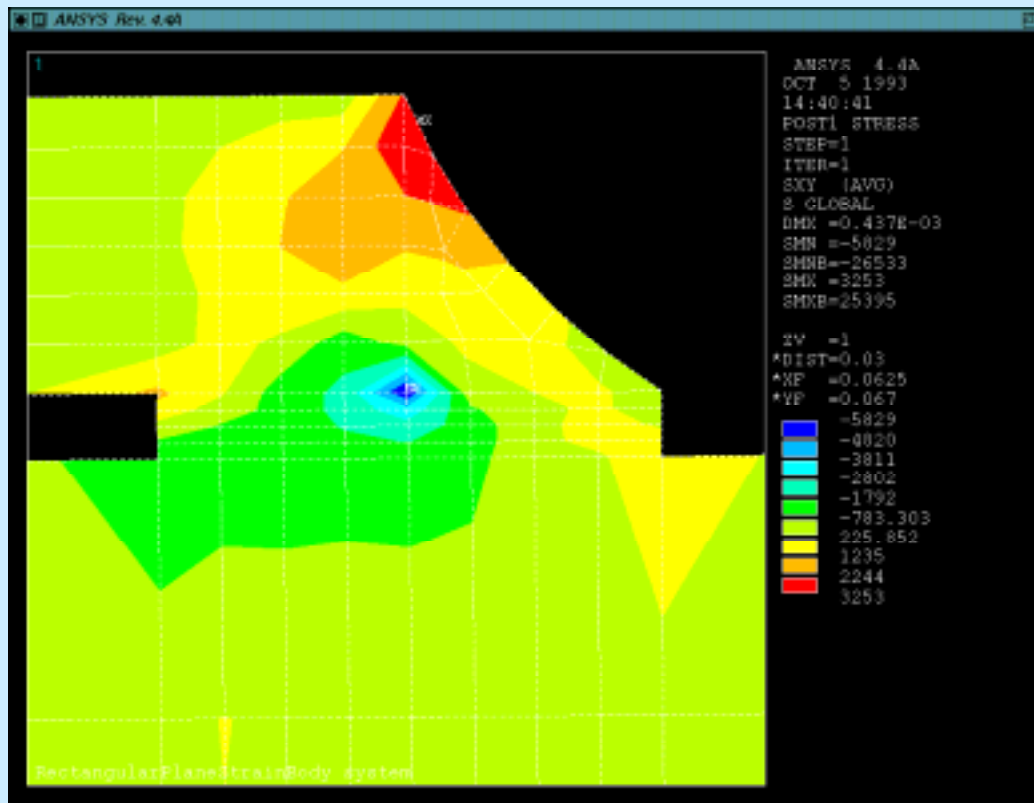




# Highly Automated Analysis

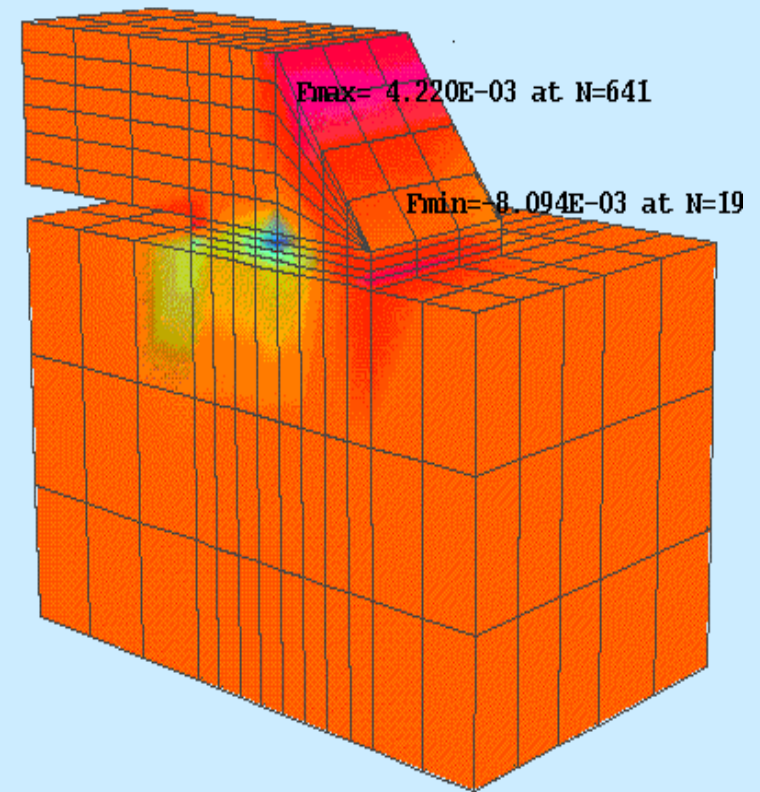
## Solder Joint Deformation

Plane Strain Model  
Shear Stress



Anslys FEA Tool

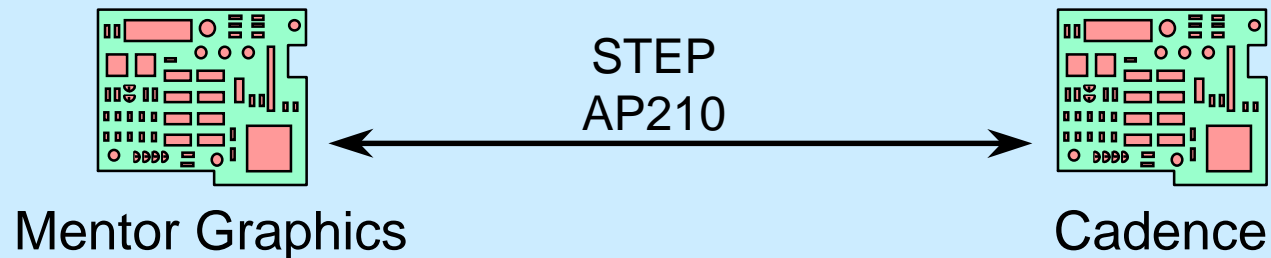
Solid Continuum Model  
Shear Strain



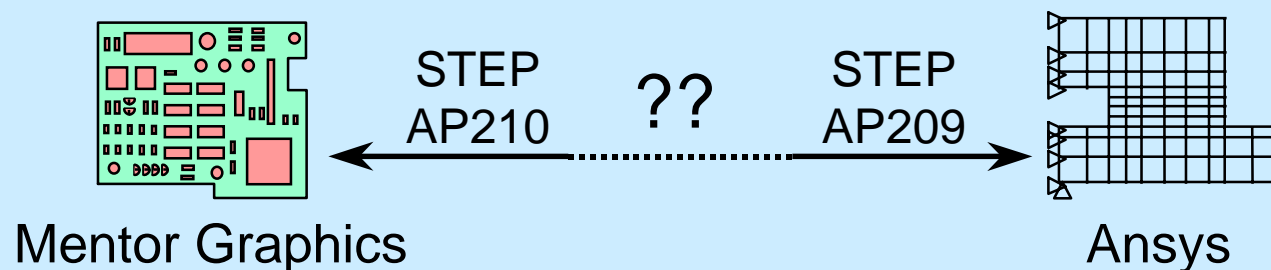
Hitachi FEA Tool

# Analysis Integration Challenges: Heterogeneous Transformations

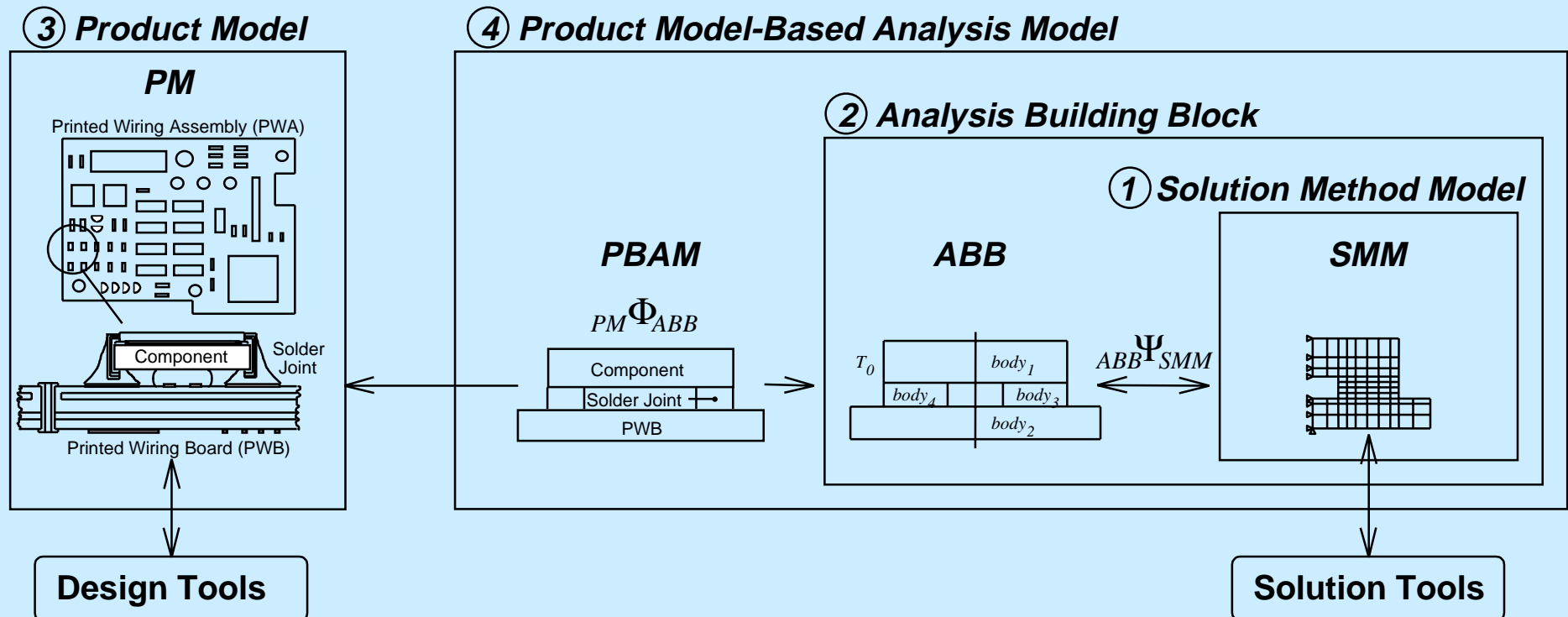
## ◆ Homogeneous Transformation



## ◆ Heterogeneous Transformation



# Multi-Representation Architecture for Design-Analysis Integration



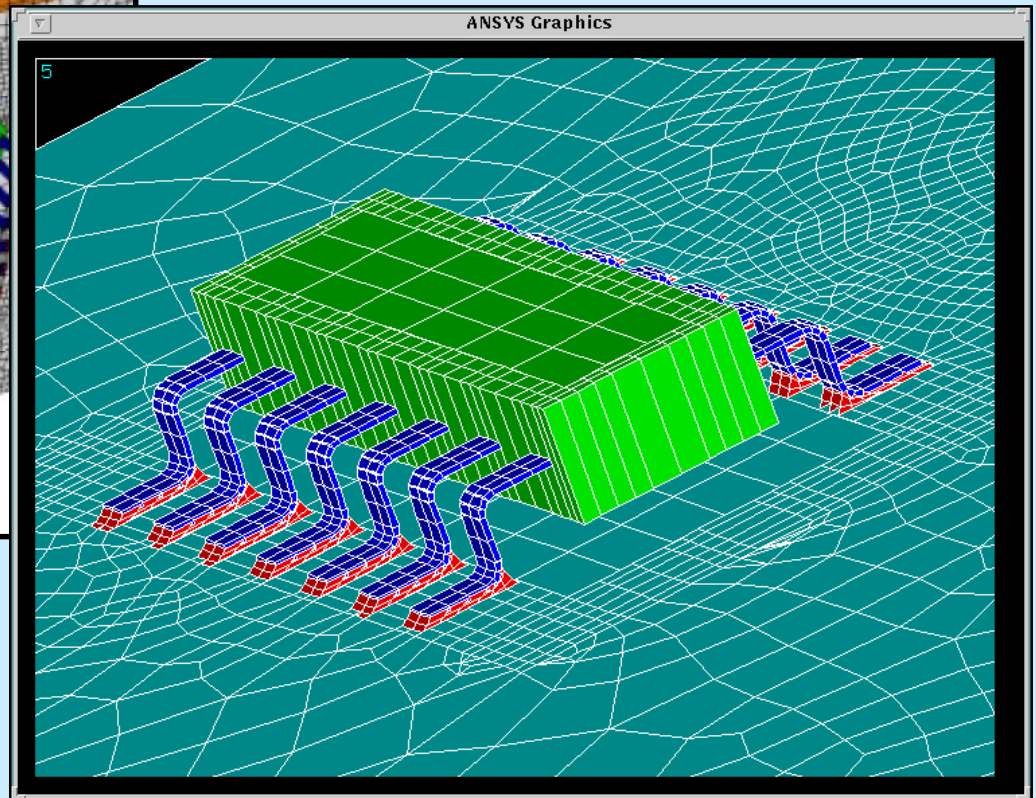
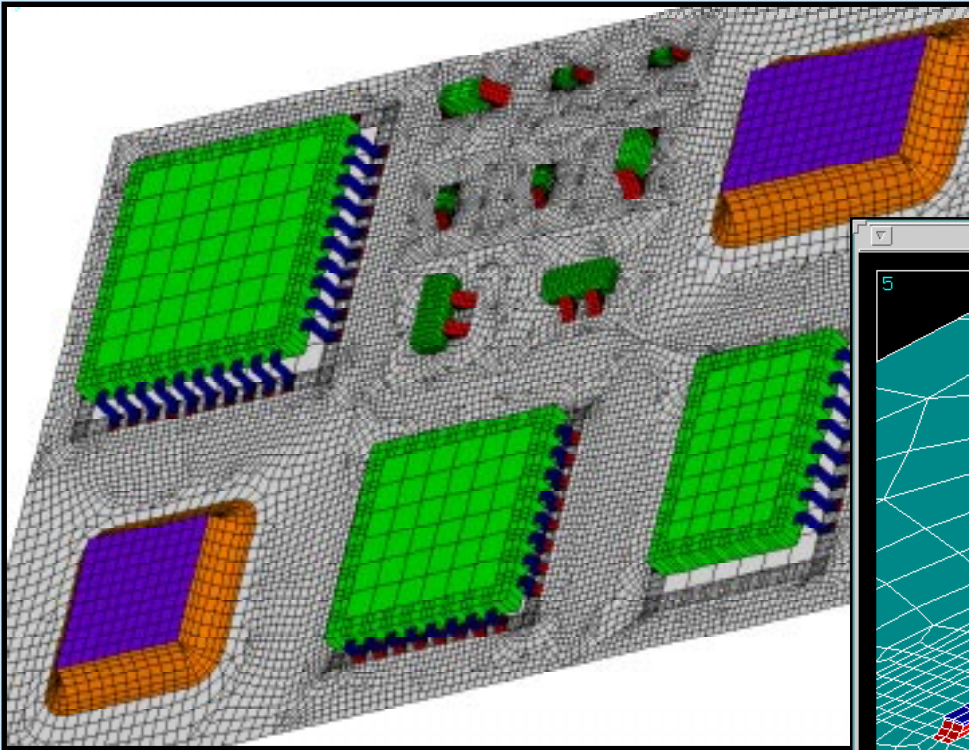
- ◆ Composed of four representations (information models)
- ◆ Provides flexible, modular mapping between design & analysis models
- ◆ Creates automated, product-specific analysis modules (PBAMs)
- ◆ Represents design-analysis associativity explicitly

# Product Data-Driven FEA

Full Board

PWA Warpage Models

SOIC-14 Close-up



# Design-Analysis Integration (DAI) Emphasis

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- ◆ Multi-Representation Architecture (MRA)
  - Addressing fundamental DAI issues
  - General methodology --> Flexibility & broad application
- ◆ TIGER experience with AP210
  - One of the world's first STEP product data-driven analysis
- ◆ Research, applications, and tech. transfer
  - Baseline integration toolkit: *DaiTools v3.0*
  - STEP pilots
  - Demonstration engineering service bureau (at Atlanta ECRC)
- ◆ Industry & government collaboration



# Integrated Product Team Solutions

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## Requirement

**Distributed Sites**

**Heterogeneous ECAD  
Systems**

**Diverse Assembly &  
Fabrication Capabilities**

**Diverse Business  
Systems**

**Issue Resolution**

**SME Limited Resources**

## Solution

**Internet Communications**

**STEP AP210  
Product Data Standards**

**STEP AP220  
Manufacturing  
Data Standards**

**EDI Standards**

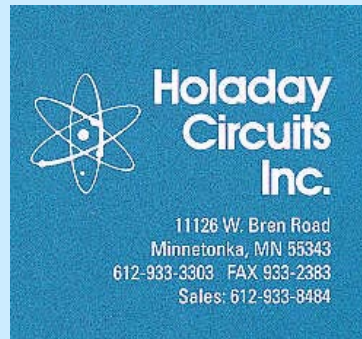
**Internet/STEP  
Negotiation Facility**

**ECRC Training/  
Service Bureau Access  
to TIGER Tools**



# Benefits for SMEs

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- **Strengthens collaborative relationship with the Prime via the Negotiation Facility**
- **Enables cost-effective access to expensive, advanced DFM & analysis tools**
- **Provides a competitive advantage in terms of product quality improvement**





# Benefits for Primes

***BOEING***

- **Strengthens the business relationship with SMEs**
- **Allows SMEs to bring more value to the IPT (Integrated Product Team)**
- **Supports the Design Anywhere, Build Anywhere philosophy**
- **Supports Digitally Driven Enterprise initiative**
- **Improves communications between engineering and manufacturing**





# Supply Chain Benefits

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- ◆ Improved part performance, reliability, & mfg. yields
- ◆ High-potential engineering service bureau paradigm
- ◆ STEP product data-driven analysis technology
- ◆ Applications to diverse product domains
- ◆ Demonstrates benefits of STEP in Tech. Data Pkgs.
  - ◆ Provides SMEs rich product models vs. raster data
  - ◆ Enables automated data-driven manufacturing
- ◆ Expedites part delivery



# Summary

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**Goal**    *Enable advanced collaboration  
between SMEs and DoD Primes*

*A STEP Towards  
Printed Circuit Design Iterations  
In About an Hour!*

*For more information, please visit the Atlanta ECRC web at <http://www.ecrc.gatech.edu/tiger/>*